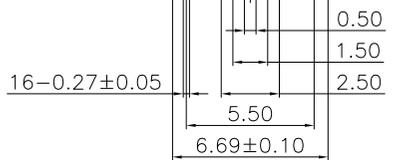
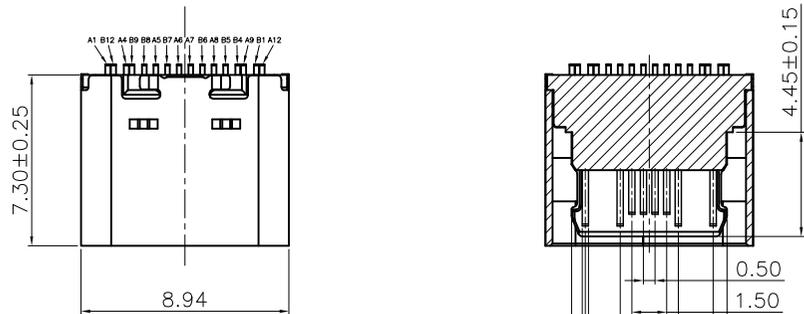
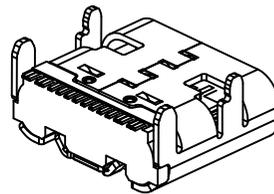


GP Component

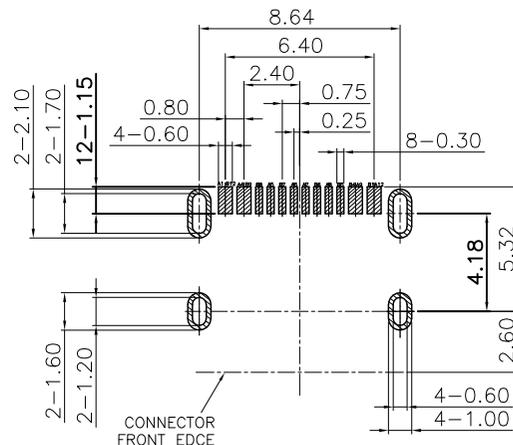
| REV. | ECN NO. | LOCATIONS | DESCRIPTION | DATE | DESIGN |
|------|---------|-----------|-------------|------------|---------|
| A0 | | | Initial | 2023/01/19 | Ken Lin |



SECTION:A-A



3D VIEW



RECOMMENDED P.C.B. LAYOUT
TOLERANCE UNSPECIFIED ±0.05mm

NOTES:

MATERIAL(材料):

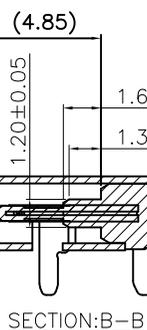
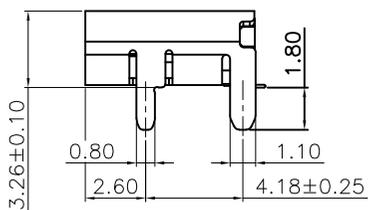
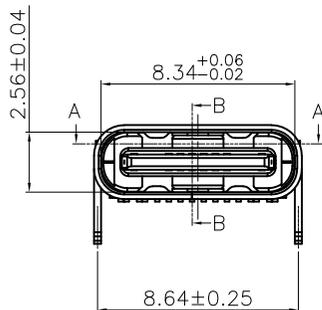
- 1.HOUSING: LCP, GLASS FIBER FILLED, BLACK
- 2.CONTACT: COPPY ALLOY (t=0.12mm).
- 3.GUARD PLATE: STAINLESS STEEL T=0.15mm
- 4.SPING: STAINLESS STEEL T=0.10mm
- 5.SHIELD: STAINLESS STEEL (t=0.20mm).

SPECIFICATION:

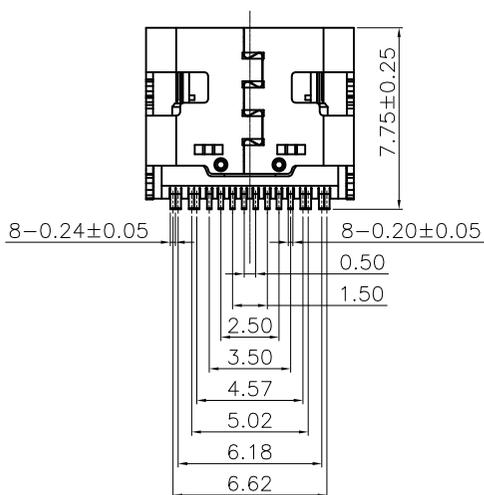
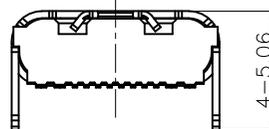
1. CURRENT RATING: 5A MAX
2. VOLTAGE: 100 VAC
3. TEMPERATURE RANGE: -25 °C ~ 85 °C
4. CONTACT RESISTANCE: 40 MILLIONHM MAX
5. INSULATION RESISTANCE: 100 MEGOHMS MIN.
6. INSERTION FORCE : 5N~20N
7. UNMATING FORCE: THE INITIAL 8~20N.
6~20N AFTER DURABILITY
8. DURABILITY:10,000 CYCLES

MATRIX PART NO:

MATRIX TYPE C **MUSB12 - 01 - 783** Series number
Plating
01:Gold Flash
15:15u"
30:30u"



SECTION:B-B



| | | | |
|-----|-------------|-----|-------------|
| A1 | GND | B12 | GND |
| A4 | VBUS | B9 | VBUS |
| A5 | CC1 | B8 | SBU2 |
| A6 | DP1 | B7 | DN2 |
| A7 | DN1 | B6 | DP2 |
| A8 | SBU1 | B5 | CC2 |
| A9 | VBUS | B4 | VBUS |
| A12 | GND | B1 | GND |
| PIN | SIGNAL NAME | PIN | SIGNAL NAME |



Matrix Electronics Co.,Ltd

| | | | | | |
|--|--|--------------------------------|----------------------|--|---------------|
| TOLERANCE: X. ±0.30 X.X ±0.25 X.XX ±0.20 ANGLE: ±3° | | DESIGN BY : Ken Lin | DATE : 2023/01/19 | PART NAME: USB2.0 TYPE-C 16P 板上短体母座(L=7.30) | |
| UNIT: mm [inch] | | CHECKED BY: Hanson Huang | DATE : 2023/01/19 | PART NO. | MUSB12-01-783 |
| SCALE:1:1 SIZE:A4 | | APPROVED BY1: Richard Hsieh | DATE : 2023/01/19 | MOLD NO. | NA |
| | | APPROVED BY2: Richard Hsieh | DATE : 2023/01/19 | DRAW NO. | |
| | | | | SHEET NO. | 1 OF 1 |